Veeco Microtech LL-250
Automatic Loadlock Ion Beam Etch System

Clean, anisotropic, high yield etching of any material including Au, Du, Ni, Cr, and TiW. Multistep etch processes for stacked layers (MLC, MCM), ceramics, hybrids, thin film heads, heads, flat panel displays, and high frequency devices.

Substrate capacity up to 8”× 8” and 10” dia., weights to 5 pounds.

Process flexibilityincludes IBE, RIBE, CAIBE, Patented “Flowcool” substrate cooling system with failsafe sensing.